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New set of claims in view of the written opinion.

1. A continuous process for the partial demetallization of a first multilayer substrate comprising an oriented coextruded polypropylene film, an adhesive layer (26) and at least one metallic layer (21) characterised in that a designed etchant lacquer (25) comprising at least one metal dissolving etchant is applied on said metallic layer (21) in a quantity close to the stoechiometrical amount needed to completely dissolve said metallic layer (21) and to eliminate any chemical reactivity of the etchant towards said adhesive layer (26), and that the dissolved metal remains within said multilayer structure, the dissolution of the metal allowing the creation of a substantially transparent window in said metallic layer (21) in a washing-free step, said partial demetallization being suitable to be carried out on standard gravure or flexo printing presses or coating equipment.

2. Process as in claim 1 characterised in that said process further comprises a lamination step of the partly demetallized multilayer substrate with at least one second substrate.

3. Process as in claim 1 or 2 characterised in that at least one of said multilayer substrates are treated by at least one coating operation and/or at least one printing operation.

4. Process as in claim 3 characterised in that said coating or printing operation is carried out on a different substrate surface than that where the demetallization is carried out, yet involving a patterned print or coating in register with the demetallized area and/or the other printed designs in or on the multilayer structure.

5. Process as in claim 1, characterised in that the amount of said etchant lacquer (25) is fine-tuned by choosing a

suitable gravure cylinder depth and/or by adapting the etchant concentration in said etchant lacquer (25) .

6. Process as in claim 1, characterised in that the demetallization step achieves a light transmission of at least 90% within the demetallized area.

7. Process as in claim 1, characterised in that the etchant concentration in the etchant lacquer (25) corresponds to a slight excess of the stoechiometrical amount of said etchant to dissolve the amount of metal present on the multilayer substrate.

8. Multilayer support obtainable by the process of claim 1, comprising windows in continuous and/or discontinuous supported metallic layers characterised in that said windows contain the total quantity of the residues resulting from the demetallization by means of an etching product.